Electronic Patent Application Fee Transmittal							
Application Number:	10	10723096					
Filing Date:	26-Nov-2003						
Title of Invention:	Molding compound						
First Named Inventor/Applicant Name:	John E. Kendall						
Filer:	Sc	Scott Chapple/Elise Nichols					
Attorney Docket Number:	62806A (1062-023)						
Filed as Large Entity							
Utility Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Extension-of-Time:							
Extension - 2 months with \$0 paid		1252	1	450	450		

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)				
Miscellaneous:								
Request for continued examination	1801	1	790	790				
	Tota	1240						